

5N1104389929

Abstract of the Disclosure

5 A circuit assembly for fabricating an air bridge structure and a method of
fabricating an integrated circuit package capable of supporting a circuit assembly
including an air bridge structure. A circuit assembly comprises an electronic chip and a
conductive structure embedded in a plurality of materials having a plurality of
vaporization temperatures. The plurality of materials is formed on the electronic chip and
the conductive structure is coupled to the electronic chip. To fabricate the circuit
assembly, a support structure, including interstices, is formed on an electronic chip. The
interstices of the support structure are filled with a material having a vaporization
10 temperature that is less than the vaporization temperature of the support structure.
Conductive structures are embedded in the support structure and the material, and a
connective structure is mounted on the support structure. Finally, the material is removed
from the interstices by heating the circuit assembly.

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09382929-08299